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Huang et al.

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(54) **IC CARD TYPE CIRCUIT MODULE**

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(**) Term: **14 Years**

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(51) **LOC (7) Cl.** **14-02**

(52) **U.S. Cl.** **D14/436; D14/437**

(58) **Field of Search** **D14/432-438,**
D14/478-480; 361/736, 737, 686, 752;
257/678, 679; 235/487-495, 441, 442, 443,
375; 283/75, 76, 901; 439/135, 140, 76.1;
D8/347

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Primary Examiner—Kay H. Chin

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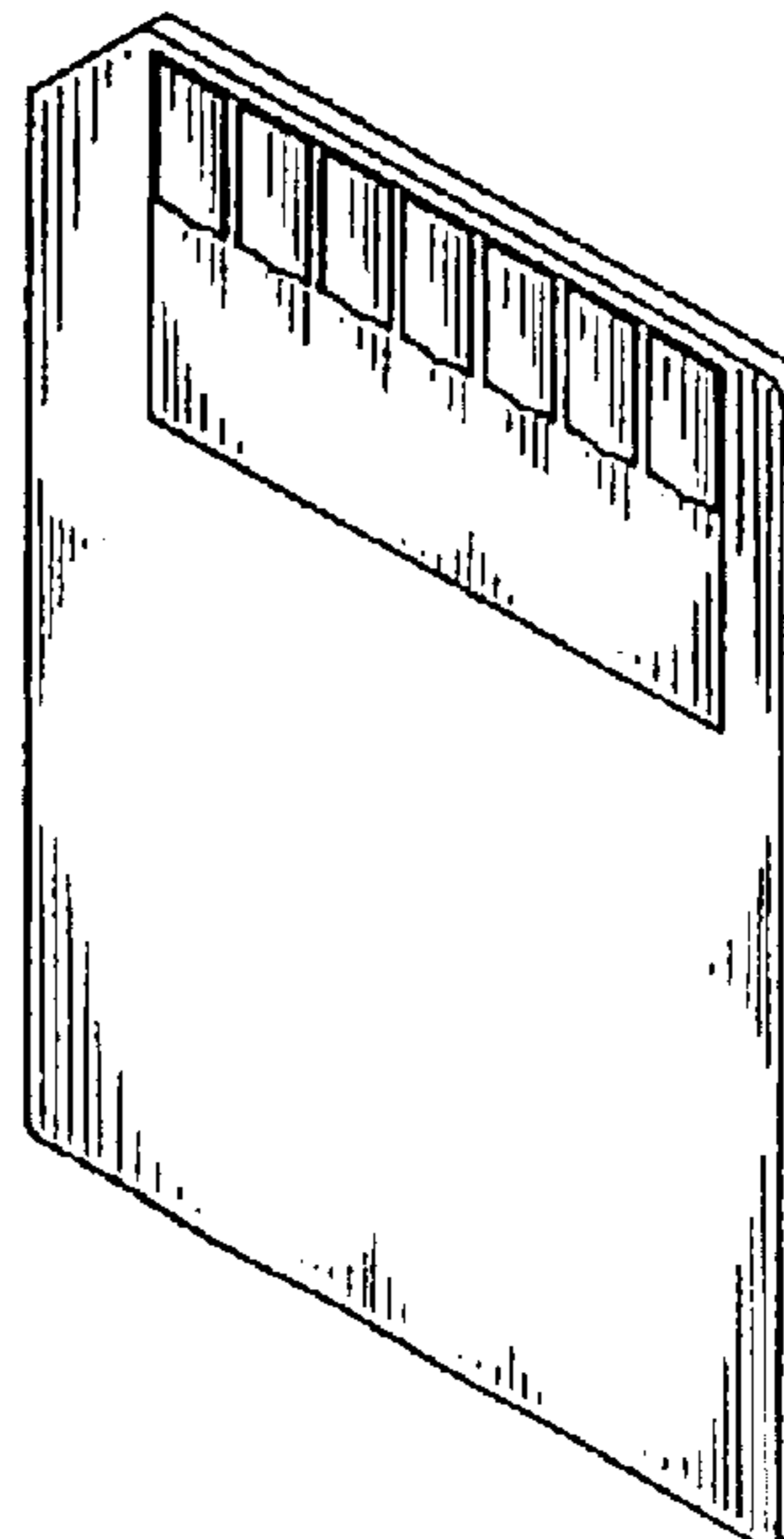
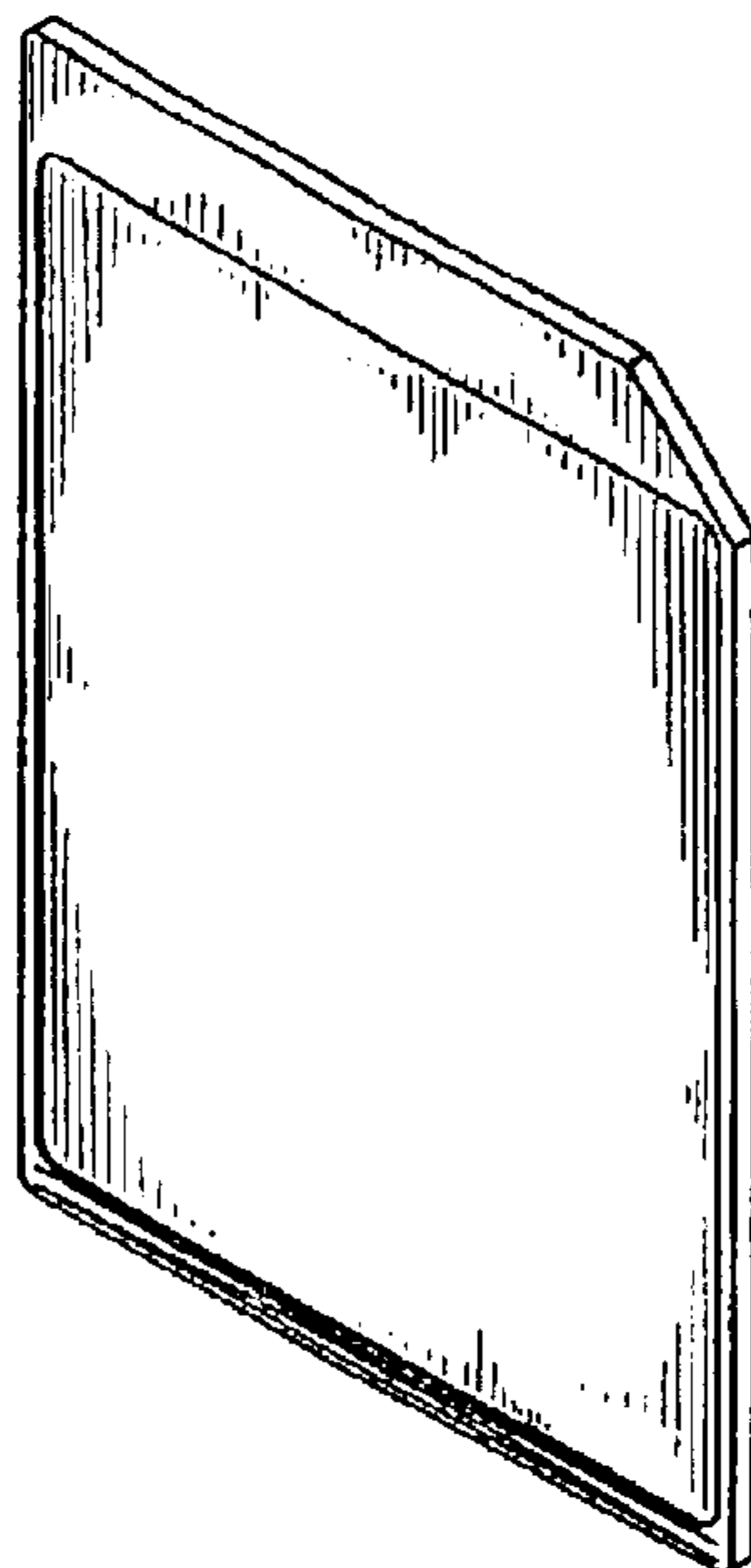
(57) **CLAIM**

The ornamental design for an IC card type circuit module, as shown and described.

DESCRIPTION

FIG. 1 is a front elevation view of an IC card type circuit module showing our new design;
FIG. 2 is a left side elevation view thereof;
FIG. 3 is a top plan view thereof;
FIG. 4 is a right side elevation view thereof;
FIG. 5 is a bottom plan view thereof;
FIG. 6 is a rear elevation view thereof;
FIG. 7 is a top perspective view thereof; and,
FIG. 8 is a bottom perspective view thereof.

1 Claim, 2 Drawing Sheets



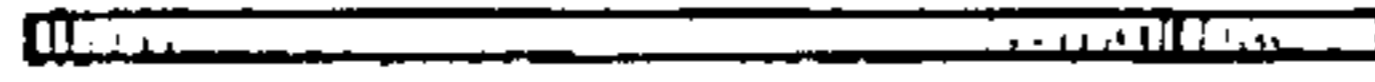


FIG. 1



FIG. 2

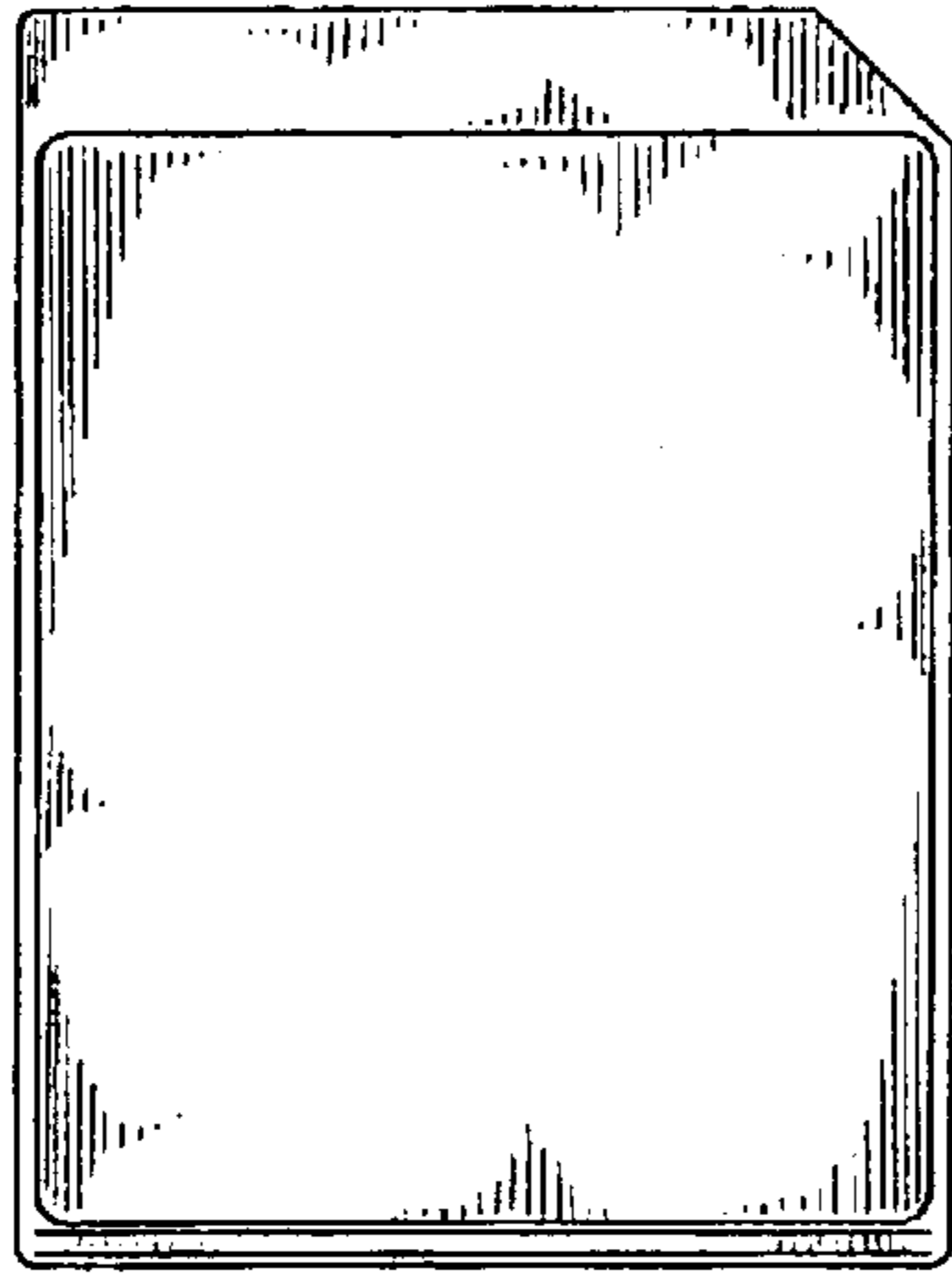


FIG. 3



FIG. 4

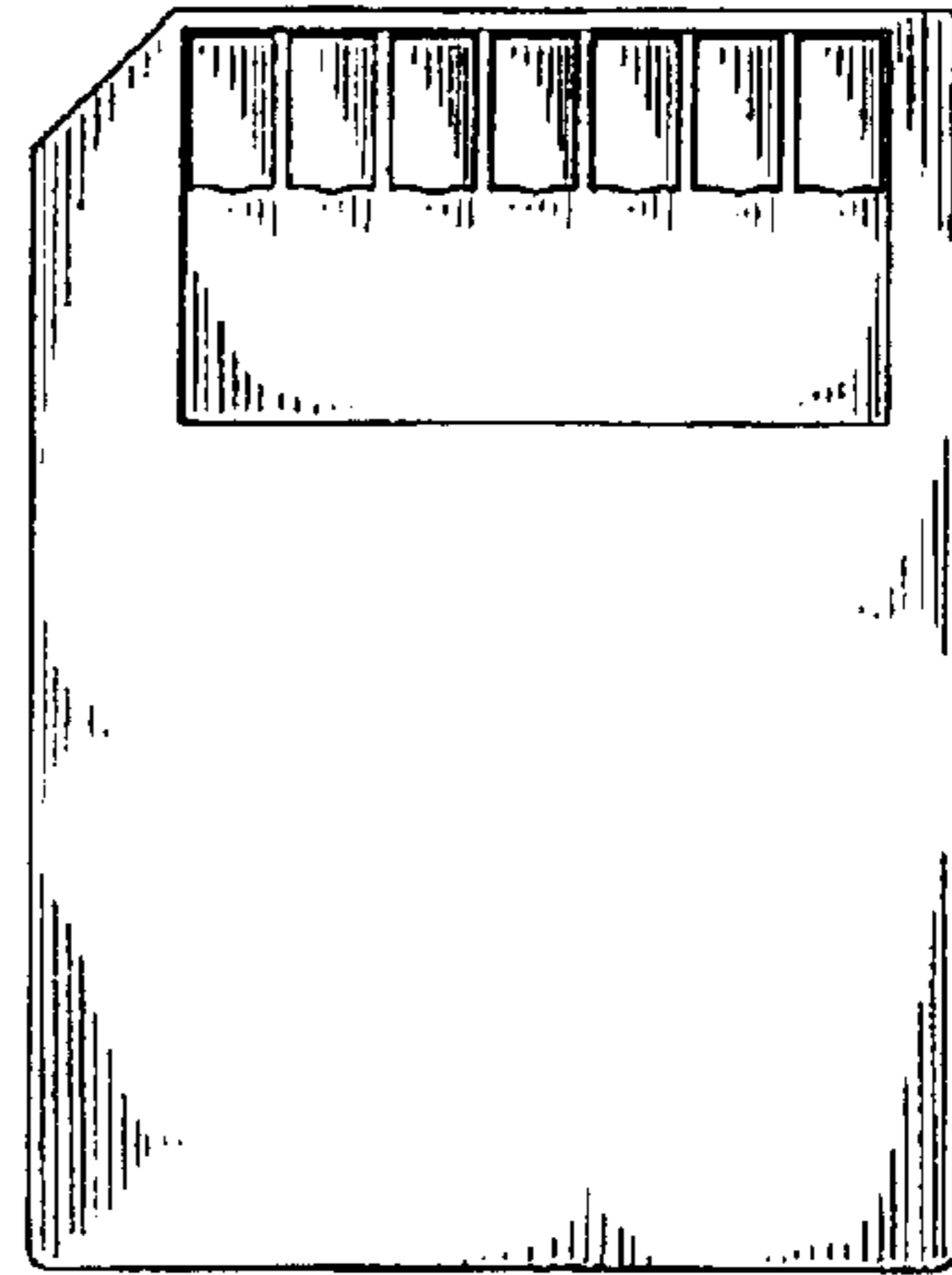


FIG. 5

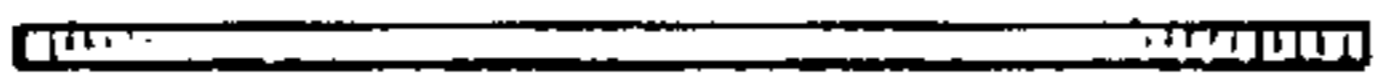


FIG. 6

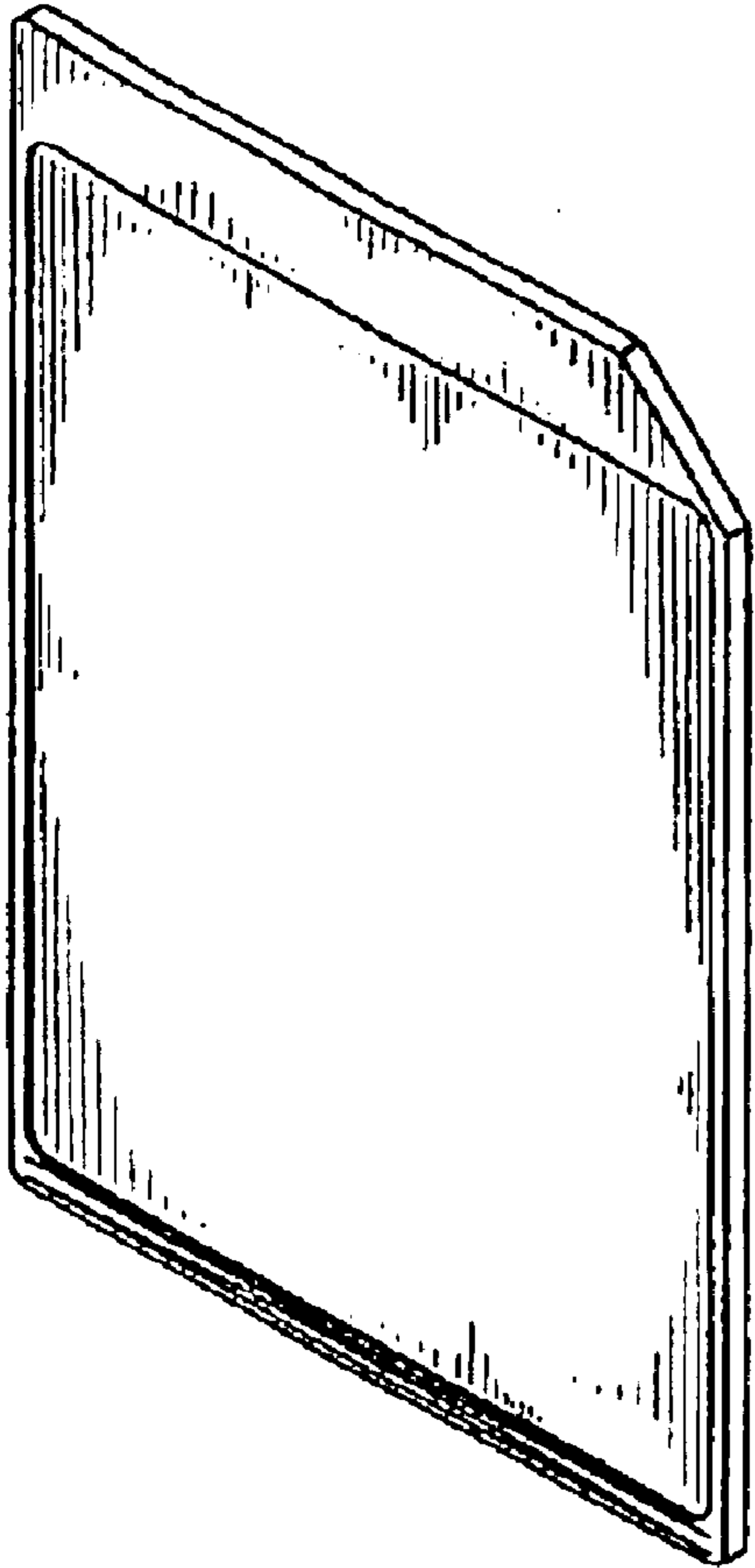


FIG. 7

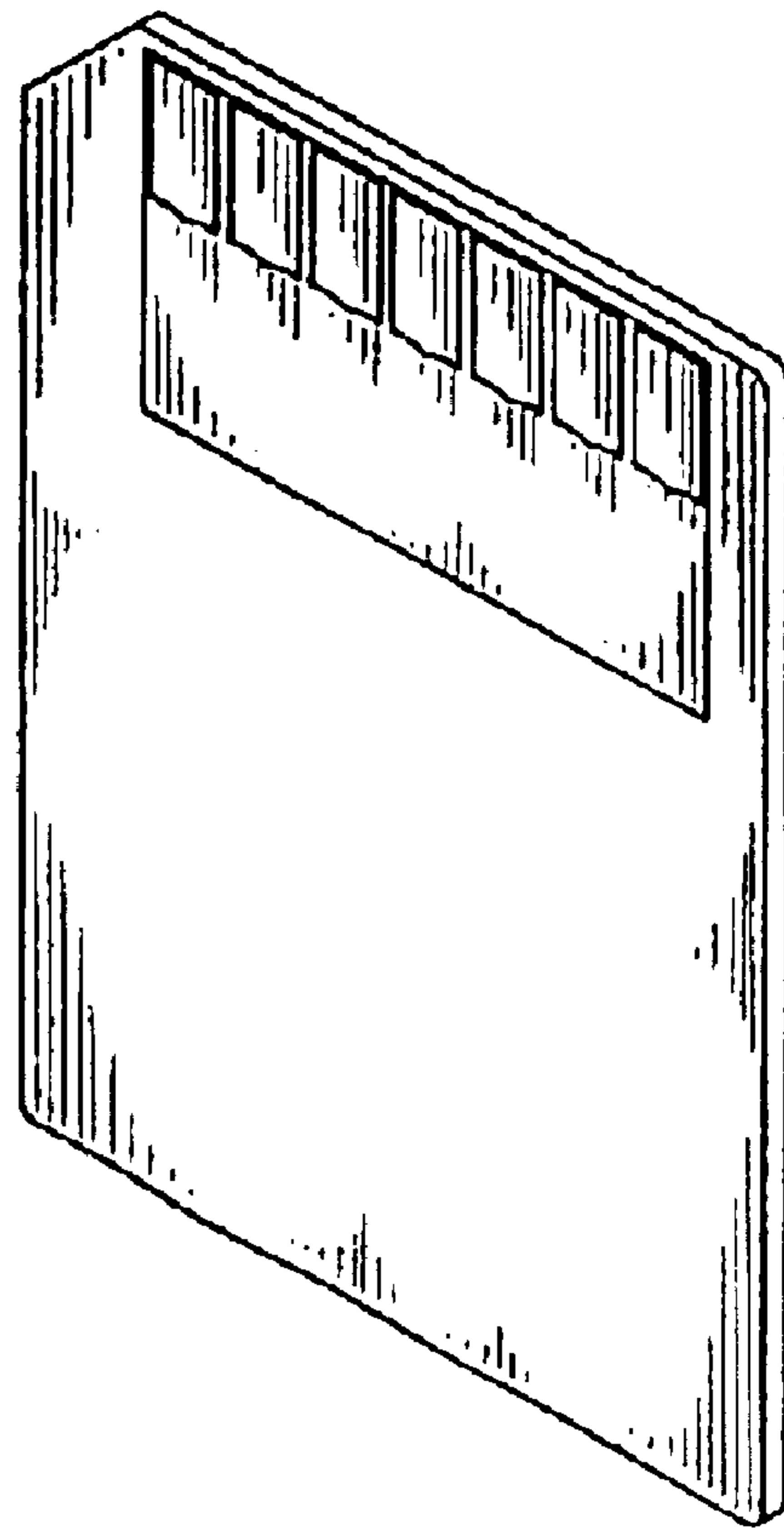


FIG. 8